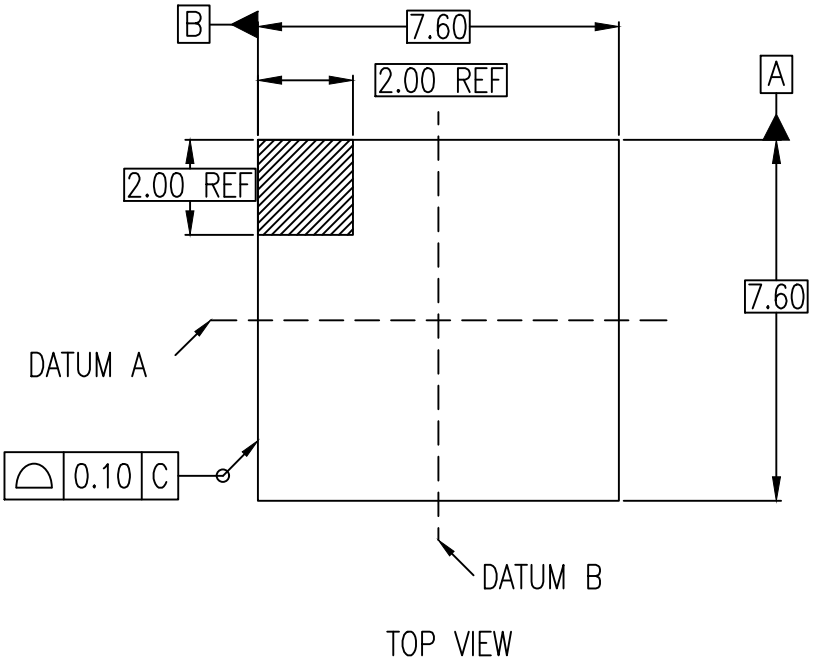
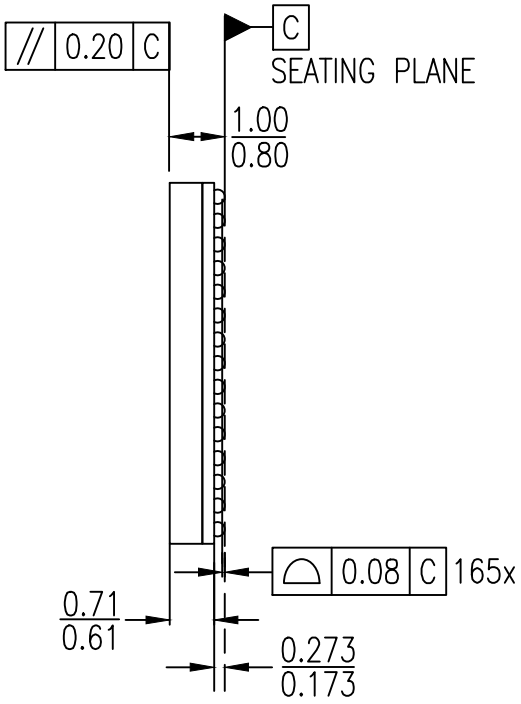
165-FCCSP, Package Outline Drawing

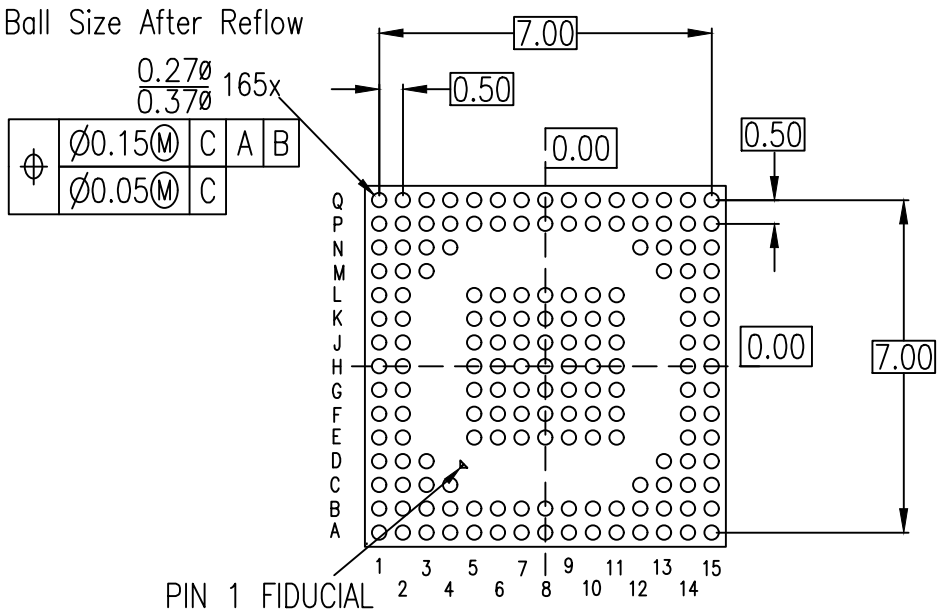
7.6 x 7.6 x 0.9 mm Body, 0.50mm Pitch,
AVG165D1, PSC-4833-01, Rev 00, Page 1



TOP VIEW



SIDE VIEW



BOTTOM VIEW
(BALL SIDE VIEW)

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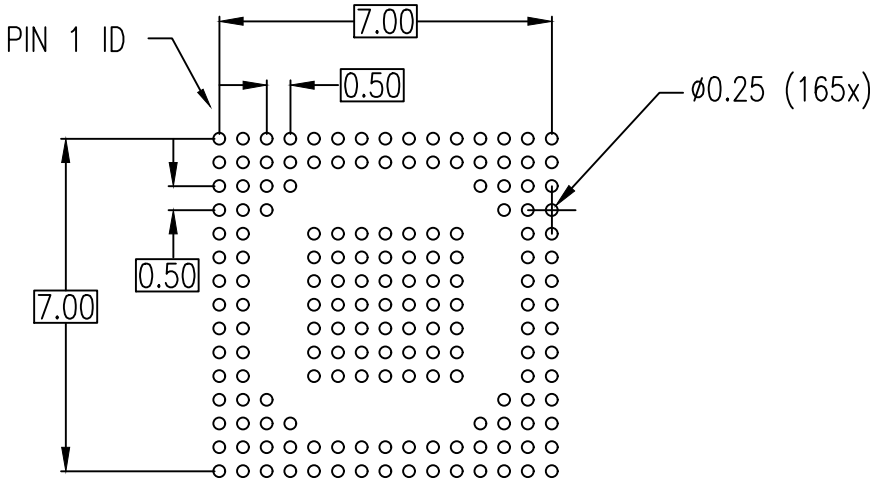

RECOMMENDED LAND PATTERN DIMENSION
(TOP VIEW)

NOTES:
1. ALL DIMENSION ARE IN MM. ANGLES IN DEGREES.
2. TOP DOWN VIEW. AS VIEWED ON PCB.
3. LAND PATTERN RECOMMENDATION PER IPC-7351B GENERIC REQUIREMENT FOR SURFACE MOUNT DESIGN AND LAND PATTERN.

Package Revision History		
Date Created	Rev No.	Description
Nov. 4 2019	Rev 00	Initial Release

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